

ABSTRACT

A semiconductor component includes a semiconductor die,
5 and an on board capacitor on the die for filtering transient
voltages, spurious signals and power supply noise in signals
transmitted to the die. The capacitor includes a first
electrode in electrical communication with a first terminal
contact for the component, and a second electrode in
10 electrical communication with a second terminal contact for
the component. The electrodes are separated by a dielectric
layer and protected by an outer protective layer of the
component. The capacitor can be fabricated using
redistribution layers on a wafer containing multiple dice.
15 The component can be used to construct systems such as multi
chip packages and multi chip modules.

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